

1	INITIAL RELEASE	JACK WU	2007/10/20
2	NEW FORM	JACK WU	2020/05/13
3			

20071020

SPECIFICATION:

1. Current Rating: 0.5A
2. Insulator Resistance: 1000MΩ Min.
3. Withstanding Voltage: 500V AC/minute
4. Contact Resistance : 40mΩ Max.
5. Temperature Rating : -40°C~+85°C

PIN DEFINE

PIN No.	PIN ASSIGNMENT
P1	DATA2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
P7	DAT0
P8	DAT1
P9	WP
P10	CD

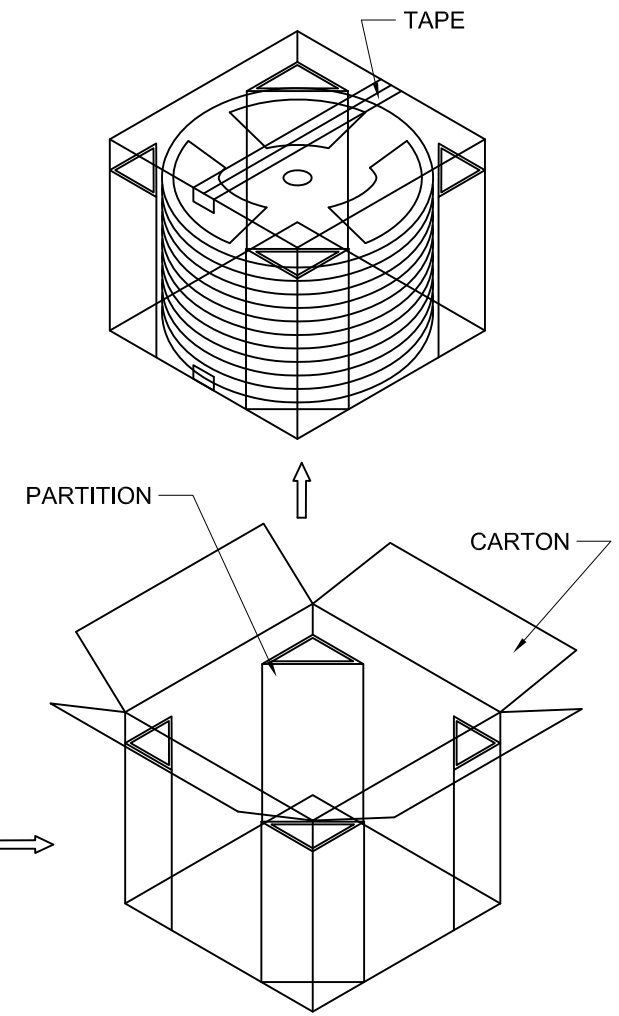
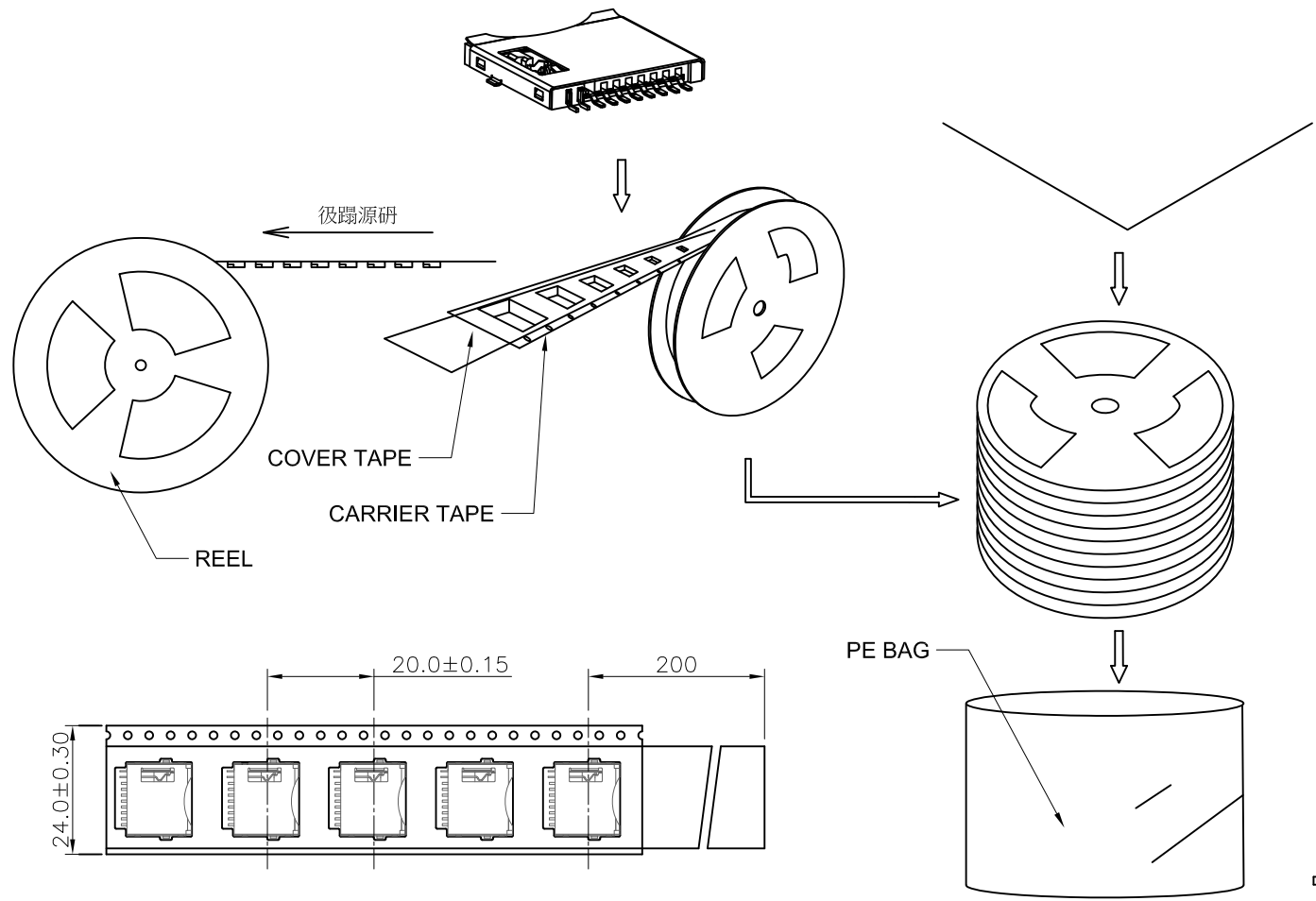
3.	CONTACT-SD	Copper Alloy, Gold Plating on Contact Area Tin Plated on Solder Area
2.	SHELL	Copper Alloy. Tin Plated on Solder Area
1.	HOUSING	LCP, UL94 V-0, Black

NO.	PART NAME	DESCRIPTION
DIMENSIONS : mm		TOLERANCES UNLESS OTHERWISE SPECIFIED :
		X. ± 0.30 X.X ± 0.20 X.XX ± 0.10 ANGLES ± 3°
SCALE	1 : 1	DWN JACK WU 20071020
SHEET	1/2	CHK PETER WANG 20071020
SIZE	A4	APVD SIMON LI 20071020
CUSTOMER DRAWING		PRODUCT No. CX1-MSD101-A61
		DRAWING No. CS-MSD006

Chunxin Technology

NAME
Micro SD Socket Push Pull Type
H=1.85mm

1	INITIAL RELEASE	JACK WU	2011/12/09
2	NEW FORM	JACK WU	2020/04/14
3			



PACKING INFORMATION

PART NAME	
QUANTITY OF PER TRAY	1000PCS/REEL
QUANTITY OF PER CARTON	10*1000=10000PCS/CARTON
WEIGHT OF PER TRAY	(1000*0.00040kg)+0.420kg=0.820Kg/REEL
WEIGHT OF PER CARTON (NET WEIGHT)	10*0.820kg=8.2Kg
GROSS WEIGHT	8.2+1.23=9.43Kg
SIZE	350*350*325

NO.	PART NAME	DESCRIPTION
DIMENSIONS : mm		Chunxin Technology NAME Micro SD Socket Push Pull Type H=1.85mm
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SCALE	DWN	20071020
1 : 1	JACK WU	20071020
SHEET	CHK	20071020
2/2	PETER WANG	
SIZE	APVD	20071020
A4	SIMON LI	
CUSTOMER DRAWING		PRODUCT No. CX1-MSD101-A61
		DRAWING No. CS-MSD006